

Abstract Submitted  
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**All Epitaxial Heterostructure for Spin Injection from a Half Metal into Silicon** MAITRI WARUSAWITHANA, DARRELL SCHLOM, Department of Materials Science and Engineering, Penn State University, JAMES ECKSTEIN, Department of Physics, University of Illinois at Urbana-Champaign — Using reactive molecular-beam epitaxy, epitaxial  $\text{La}_{0.7}\text{Sr}_{0.3}\text{MnO}_3$  /  $\text{SrTiO}_3$  / Si heterostructures have been grown. The  $\text{SrTiO}_3$  layer, just a few unit cells thick, serves simultaneously as a tunnel barrier and as a means to reduce reaction between the  $\text{La}_{0.7}\text{Sr}_{0.3}\text{MnO}_3$  and the underlying Si. The growth of  $\text{La}_{0.7}\text{Sr}_{0.3}\text{MnO}_3$  at MBE-compatible pressures requires ozone, which readily oxidizes bare Si and would destroy the chances for epitaxial growth. In contrast, epitaxial  $\text{SrTiO}_3$  can be grown on (001) Si using molecular oxygen via a complex, but established process. Once the  $\text{SrTiO}_3$  film is complete, ozone is turned on for the  $\text{La}_{0.7}\text{Sr}_{0.3}\text{MnO}_3$  growth. The thin  $\text{SrTiO}_3$  layer acts as a diffusion barrier for oxygen limiting the formation of  $\text{SiO}_2$  at the  $\text{SrTiO}_3/\text{Si}$  interface. X-ray diffraction measurements show that the  $\text{La}_{0.7}\text{Sr}_{0.3}\text{MnO}_3$  layer has good crystalline quality with rocking curve full width at half maximum values of the 200 peak of less than  $0.5^\circ$ . Furthermore, electrical transport measurements indicate that the  $\text{La}_{0.7}\text{Sr}_{0.3}\text{MnO}_3$  layer is ferromagnetic and metallic below  $\sim 370$  K with a resistivity  $< 100 \mu\Omega\text{-cm}$  at 4.2 K. Possible devices for tunneling spins into Si and for detecting spin carrier density inside a Si channel will be discussed.

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